



# 100V N-Channel SGT Power MOSFET

## General Description

The SJ016N10A uses SGT technology to provide excellent  $R_{ds(on)}$ , low gate charge and fast switching characteristics. This device is suitable for use as a wide variety of applications.

## Features

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handling capability
- Lead free product is acquired

## Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

## Key Performance Parametes

Parameter	Value	Unit
$V_{DS}$	100	V
$R_{DS(ON\_TYP)}$	1.8	m $\Omega$
$I_D$	287	A
$Q_G$	135	nC



## Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJ016N10A	SJ016N10A	TO-220	Tube	\	\	1000 Pcs

**Table 1. Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Limit	Unit
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0V$ )	100	V
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0V$ )	$\pm 20$	V
$I_D$	Drain Current-Continuous( $T_C=25^\circ\text{C}$ )	287	A
	Drain Current-Continuous( $T_C=100^\circ\text{C}$ )	181	A
$I_{DM}$ (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	1148	A
$P_D$	Maximum Power Dissipation( $T_C=25^\circ\text{C}$ )	313	W
	Maximum Power Dissipation( $T_C=100^\circ\text{C}$ )	125	W
$E_{AS}$	Avalanche energy (Note 2)	1849	mJ
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 150	$^\circ\text{C}$

**Table 2. Thermal Characteristic**

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.4	$^\circ\text{C/W}$



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**Table 3. Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=100V, V_{GS}=0V, T_J=25^\circ\text{C}$			1	$\mu A$
		$V_{DS}=100V, V_{GS}=0V, T_J=125^\circ\text{C}$			100	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2		4	V
$g_{FS}$	Forward Transconductance	$V_{DS}=10V, I_D=20A$		35		S
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=20A, T_J=25^\circ\text{C}$		1.8	2.3	m $\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=50V, V_{GS}=0V, f=1.0\text{MHz}$		9820		pF
$C_{oss}$	Output Capacitance			3920		pF
$C_{rss}$	Reverse Transfer Capacitance			109		pF
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1.0\text{MHz}$		3.2		$\Omega$
<b>Switching Parameters</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DS}=50V, R_L=2.5\Omega, R_{GEN}=6\Omega$		35		nS
$t_r$	Turn-on Rise Time			62		nS
$t_{d(off)}$	Turn-Off Delay Time			142		nS
$t_f$	Turn-Off Fall Time			110		nS
$Q_g$	Total Gate Charge	$V_{GS}=10V, V_{DS}=50V, I_D=20A$		135		nC
$Q_{gs}$	Gate-Source Charge			43		nC
$Q_{gd}$	Gate-Drain Charge			31		nC
<b>Source-Drain Diode Characteristics</b>						
$I_{SD}$	Source-Drain Current (Body Diode)				287	A
$V_{SD}$	Forward on Voltage (Note 3)	$V_{GS}=0V, I_S=20A$			1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=20A, dI/dt=500A/\mu s$		70		ns
$Q_{rr}$	Reverse Recovery Charge	$I_F=20A, dI/dt=500A/\mu s$		120		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

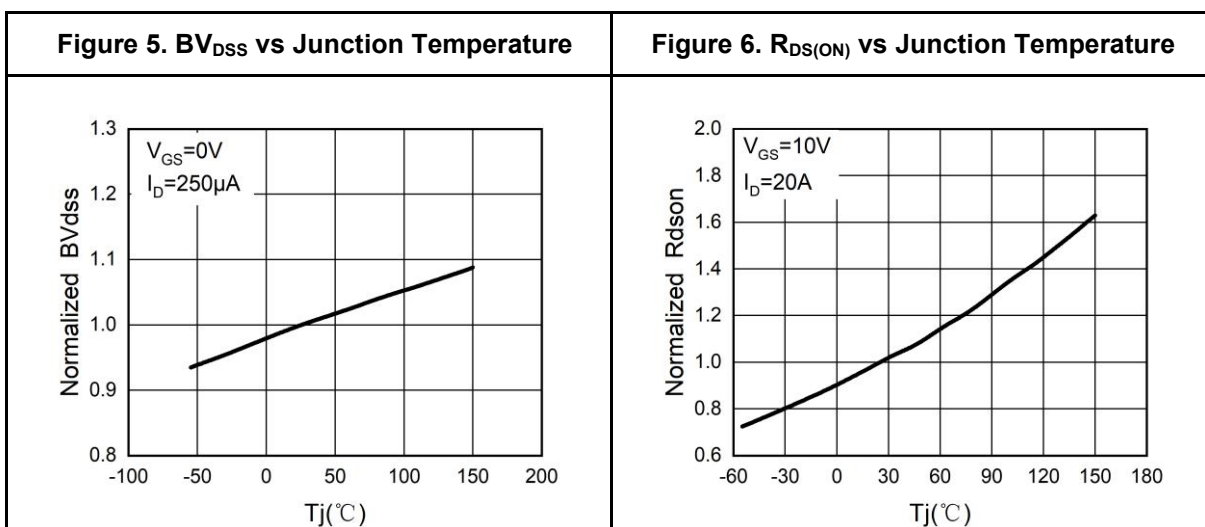
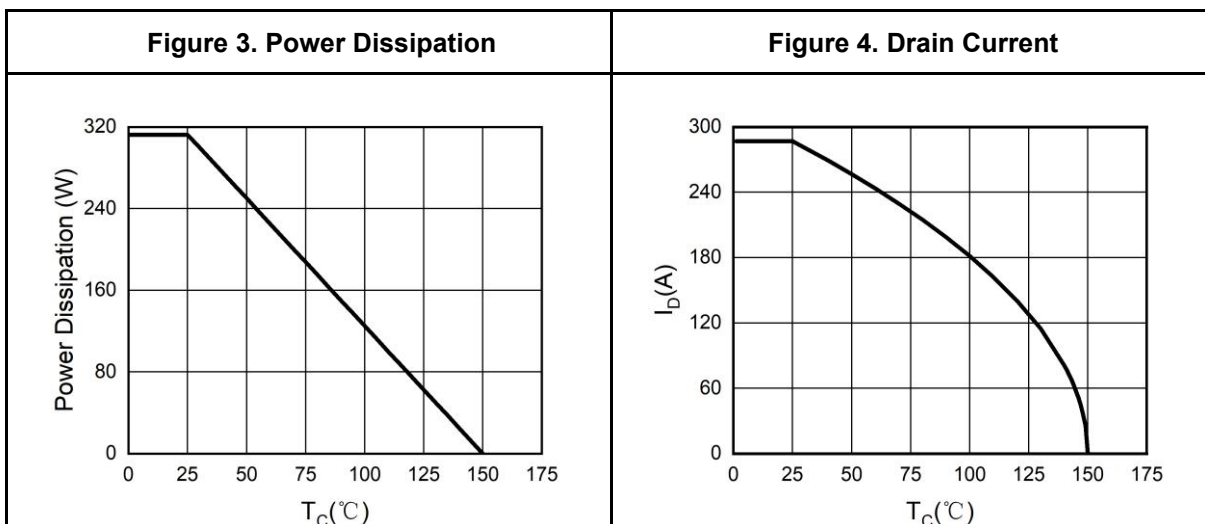
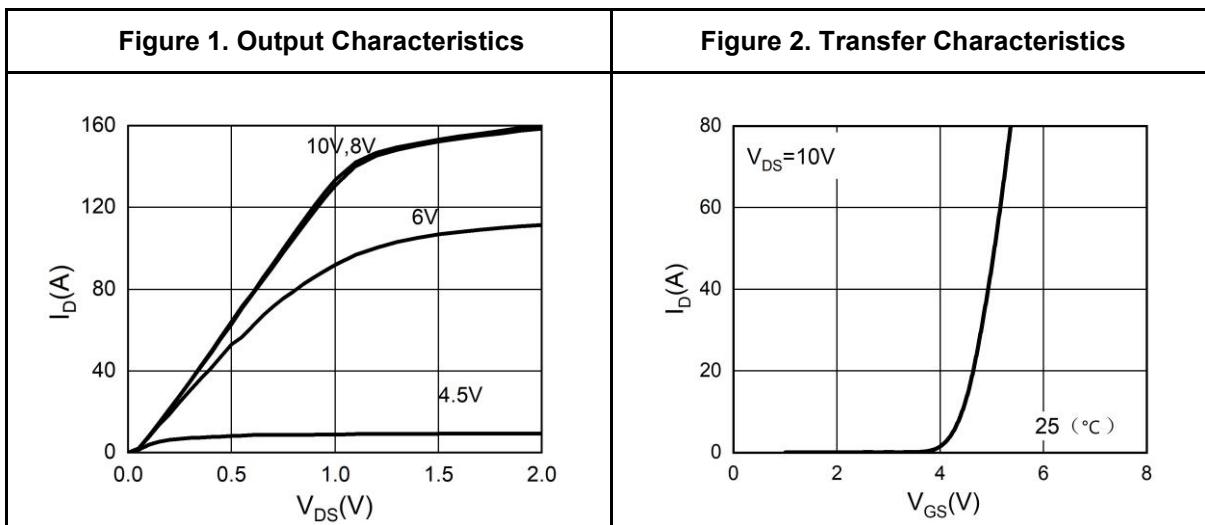
Notes 2.EAS condition:  $T_J=25^\circ\text{C}, V_{DD}=50V, V_G=10V, R_g=25\Omega, L=0.5\text{mH}$ .

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



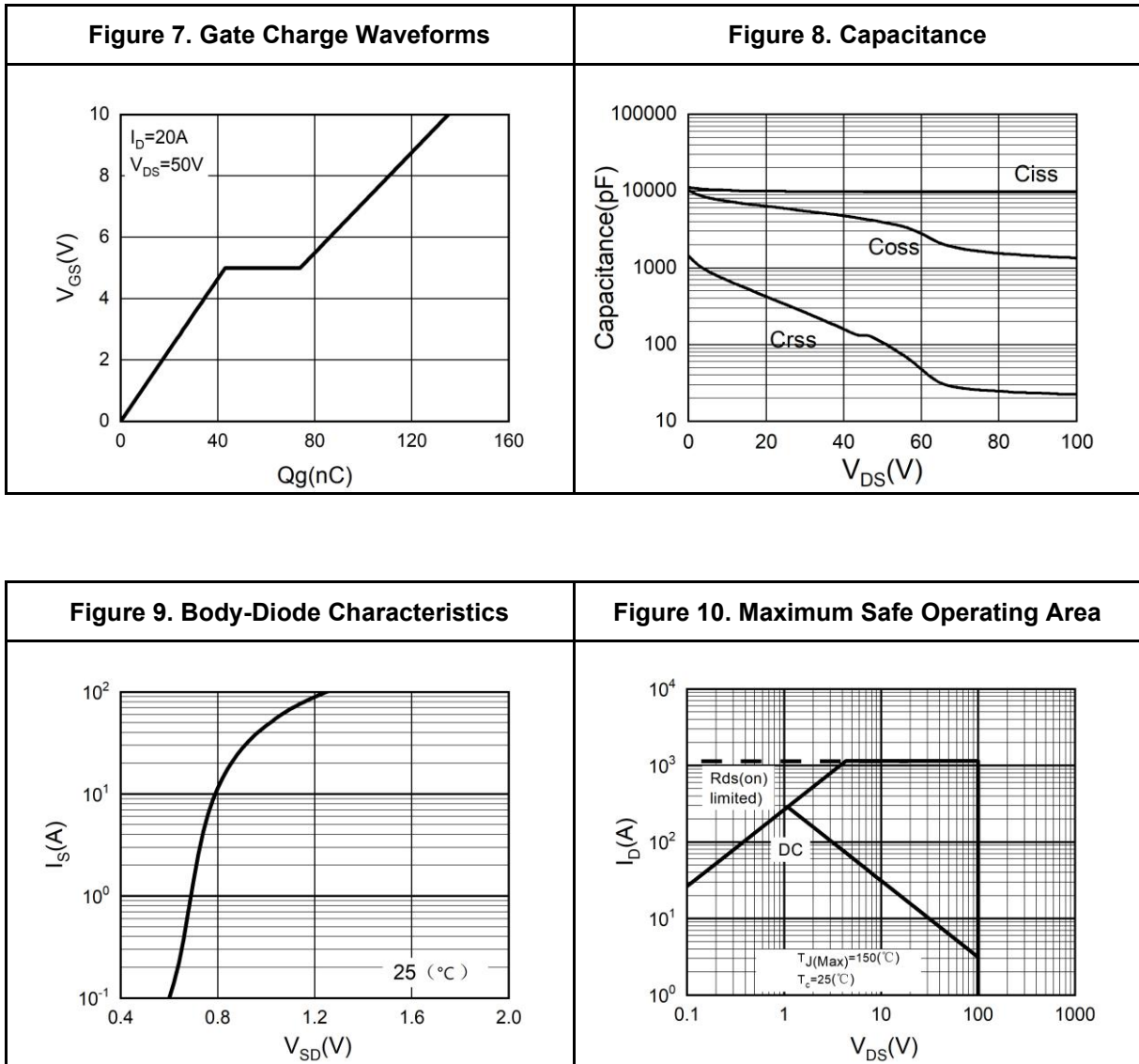
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## Typical Electrical And Thermal Characteristics (Curves)





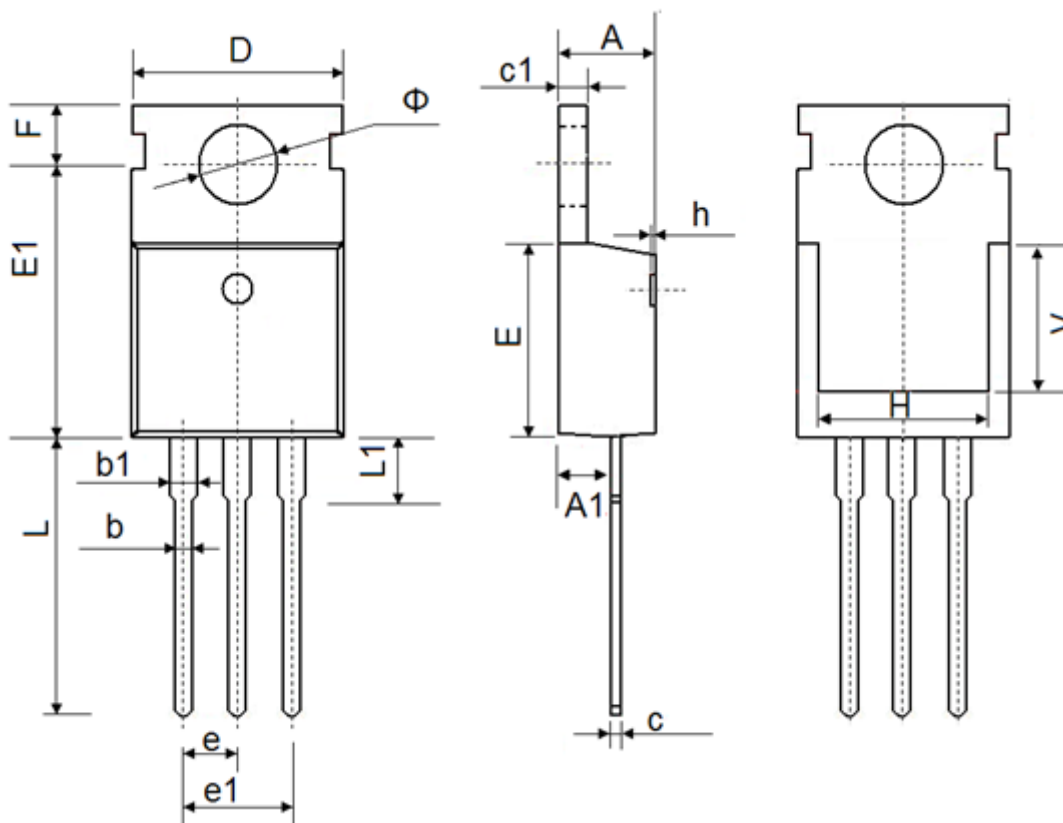
Typical Electrical And Thermal Characteristics (Curves)





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TO-220 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
c	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
E	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500 REF.		0.295 REF.	
Φ	3.400	4.000	0.134	0.157



## **Attention**

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